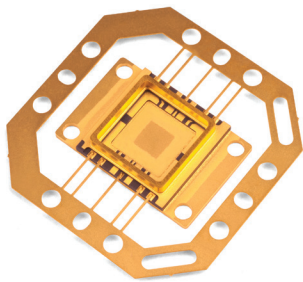


CONSUMABLE DIVISION

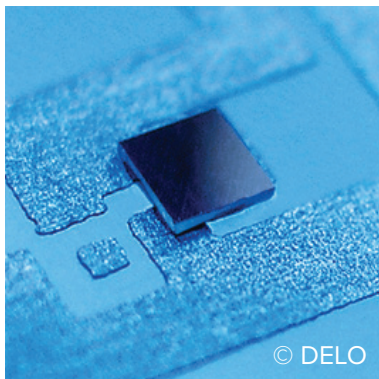
Inseto's Consumable Division provides assembly materials and machine consumables for the research and production of Semiconductor, Microelectronic and related advanced electronic devices etc., as well as products for high technology & industrial manufacturing.

Products & services include: semiconductor & silica wafers, sub-contract wafer bumping grinding & dicing, bonding wires & ribbons, plated wire & ribbons, precision stampings, solder spheres & preforms, hermetic glass & ceramic packages, thick film materials, metalised thin film substrates, thermal dissipation materials, welding electrodes & thermodes, plus bonding wedges, capillaries, die collets & dicing blades etc.



CERAMIC & GLASS TO METAL SEALED MICROELECTRONIC PACKAGES BY EGIDE

- Power packages
- RF and microwave packages
- Thermal imaging HTCC packages
- Optoelectronic, bathtub and flatpacks
- European-based manufacturer



DELO DIE ATTACH AND ENCAPSULATION ADHESIVES

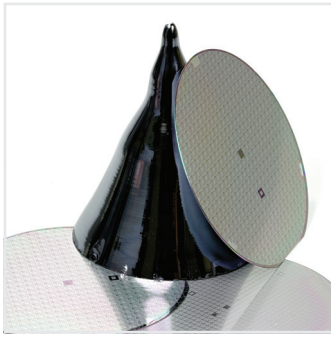
- Fast curing epoxy adhesives
- Optional light-fixing capability
- High temperature resistance, up to 250°C
- Suitable for various substrates including leadframes, FR4 & ceramic
- Conductive & non-conductive materials
- Dam & fill and glob top encapsulation adhesives



BONDING WIRE & RIBBON FROM COINING

- Gold bonding wire
- Al/Si fine wire
- Large diameter aluminium bonding wire
- Copper bonding wire
- Gold, aluminium and copper ribbon
- Plated wire and ribbon

INSETO CONSUMABLE DIVISION



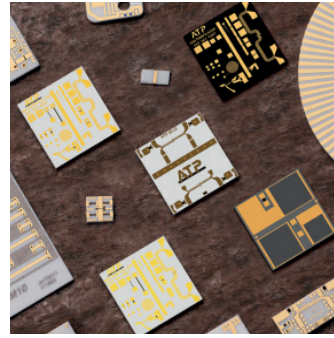
SEMICONDUCTOR WAFERS AND SUBSTRATES BY INSETO

- Si Wafer sizes from 1" to 300mm
- SEMI standard Prime Silicon
- Oxide & Nitride Coated Wafers
- Coating with Metal Layers
- 2"-200mm Glass & Fused Silica
- Edge rounded for safe secure handling
- Large UK Stock with next day delivery



DICING BLADES & ACCESSORIES BY ADT

- Resin-bond Dicing Blades
- Nickel Bonded Dicing Blade
- Metal-bond (Sintered) Blades
- Flanges & Accessories
- Dicing Equipment
- The dicing blades are composed of abrasive materials embedded in either resin or metal matrix



METALISED THIN FILM CIRCUITS BY ATP

- Complete In-House Thin-Film Circuit Fabrication Service
- Pattern Generated Photomasks
- In-House Resistor Laser Trimming and CO2 Laser Drilling
- Multiple Sputtering Systems and Plating Capabilities
- Air Bridges/Crossovers with Polyimide and Solder Dams



THICK FILM MICROELECTRONIC INKS / PASTES BY KOARTAN

- AlN Materials - Resistors, Conductors & Glazes etc.
- Conductors - Gold, Silver, Palladium Silver, Platinum Silver, Pt-Pd:Ag
- Resistors & Thermistors - Thick Film Resistors & Thermistors
- Dielectrics & Glazes - Multi-layer, Capacitors, Glazes & Sealing Glasses



THERMAL MANAGEMENT MATERIALS & MULTI-LAYER CERAMIC PACKAGES BY SANTIER

- Thermal Management Metal Matrix Materials
- Multi-Layer Co-Fired Ceramic Packages
- Unique products in such fields as Wireless Communication and Fibre-Optics



BONDING CAPILLARIES & DICING BLADES BY KULICKE & SOFFA

- Ball Bond Capillaries - capillaries for Au & Cu wire
- Hub Dicing Blades - for package and wafer singulation
- Kulicke & Soffa Bonding Equipment - bench mounted wire bonders, gold wire bonders, copper and automatic die bonding systems



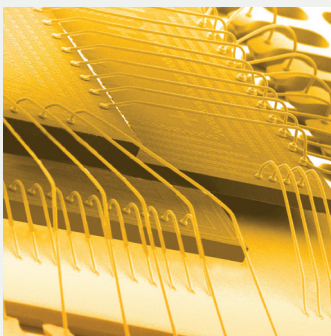
BONDING WEDGES, DIE COLLETS AND PICKUP TOOLS FROM MPP

- Ultrasonic Wedge Bonding Tools - standard and custom wedge tools to fit all applications
- Die Bonding Tools & Collets - die collets and pick up tools, manufactured from various metallic and non-metallic materials



WELDING ELECTRODES & REFLOW THERMODES BY AIT

- Welding Electrodes
- Reflow Soldering Thermodes
- Evaluation samples available
- Shorter delivery lead times
- Lower prices than the OEM
- Our quality is guaranteed
- Custom designs are no problem



Established in 1987, and ISO-Certified since 2005, Inseto supplies equipment, materials and consumables to microelectronic manufacturers and research institutes in the UK, Ireland and Nordic Regions.

Customer support activities are at the centre of Inseto's "Total Customer Service" philosophy, where we aim to understand, communicate and fulfil the needs of our customers, better than any competitor. We are committed to meeting these requirements through the application of high standards of quality and customer care, both before and after sales, by continually investing in training & adopting a policy of continuous improvement in our Company and its people.